

PMEG060T080CLPE-Q

60 V, 2 x 4 A dual common cathode low leakage current Trench MEGA Schottky barrier rectifier

10 May 2021

Product data sheet

1. General description

Trench Maximum Efficiency General Application (MEGA) dual Schottky barrier rectifier in common cathode configuration encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Reverse voltage: V_R ≤ 60 V
- Forward current: I_F ≤ 4 A (per diode)
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- Power and flat lead SMD plastic package
- Package height typical 0.95 mm
- High power capability due to clip-bond technology
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- · Low voltage rectification
- · High efficiency DC-to-DC conversion
- · Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Freewheeling applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
Per diode (unle	Per diode (unless otherwise specified)							
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} \leq 160 °C		-	-	4	А	
V _R	reverse voltage	T _j = 25 °C		-	-	60	V	
V _F	forward voltage	I _F = 4 A; T _j = 25 °C	[1]	-	580	660	mV	
I _R	reverse current	V _R = 10 V; T _j = 25 °C	[1]	-	0.14	0.9	μΑ	
		V _R = 60 V; T _j = 25 °C	[1]	-	0.3	1.8	μΑ	

[1] Very short pulse, in order to maintain a stable junction temperature.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)		CC
2	A2	anode (diode 2)	5	
3	CC	common cathode	3 [
			CFP15B (SOT1289B)	A1 A2
				006aab034

6. Ordering information

Table 3. Ordering information

Type number	Package						
	Name	Description	Version				
PMEG060T080CLPE-Q		plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	SOT1289B				

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG060T080CLPE-Q	060T
	L08C

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134).

Parameter	Conditions		Min	Max	Unit
ess otherwise specified)				•	
reverse voltage	T _j = 25 °C		-	60	V
forward current	δ = 1; T _{sp} ≤ 156 °C		-	5.7	Α
average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 160 °C		-	4	А
non-repetitive peak forward current	t_p = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	80	Α
	t _p = 8.3 ms; half sine wave; per device; T _{j(init)} = 25 °C		-	150	А
e diode loaded		•		•	
total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1.66	W
		[2]	-	2.15	W
junction temperature			-	175	°C
ambient temperature			-55	175	°C
storage temperature			-65	175	°C
	reverse voltage forward current average forward current non-repetitive peak forward current e diode loaded total power dissipation junction temperature ambient temperature	reverse voltage $T_j = 25 ^{\circ}\text{C}$ forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \leq 160 ^{\circ}\text{C}$ non-repetitive peak forward current $\delta = 0.5$;	reverse voltage $T_{j} = 25 ^{\circ}\text{C}$ forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \leq 160 ^{\circ}\text{C}$ non-repetitive peak forward current $t_{p} = 8.3 \text{ms}$; half sine wave; $T_{j(\text{init})} = 25 ^{\circ}\text{C}$ $t_{p} = 8.3 \text{ms}$; half sine wave; per device; $T_{j(\text{init})} = 25 ^{\circ}\text{C}$ e diode loaded $t_{p} = 0.3 \text{ms}$ total power dissipation $t_{p} = 0.3 \text{ms}$ for $t_{p} = 0.3 \text{ms}$; half sine wave; per device; $t_{p} = 0.3 \text{ms}$ for $t_{p} = 0.3 \text{ms}$ f	reverse voltage $T_j = 25 ^{\circ}\text{C}$ - forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ - average forward current $\delta = 0.5$; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $T_{sp} \leq 0.5$; $T_{sp} \approx 0.$	reverse voltage $T_j = 25 ^{\circ}\text{C}$ - 60 forward current $\delta = 1$; $T_{sp} \le 156 ^{\circ}\text{C}$ - 5.7 average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \le 160 ^{\circ}\text{C}$ - 80 non-repetitive peak forward current $t_p = 8.3 \text{ms}$; half sine wave; $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 80 forward current $t_p = 8.3 \text{ms}$; half sine wave; per device; $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 150 redicted loaded $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 1.66 redicted power dissipation $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 1.75 ambient temperature - 1.75 redicted $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ redicted $t_{j(\text{init})} = 25 ^$

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

^[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
	e diode loaded				- 7 P	1110011	01
rei device, oii	e diode ioaded						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	90	K/W
			[1] [3]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	7	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.

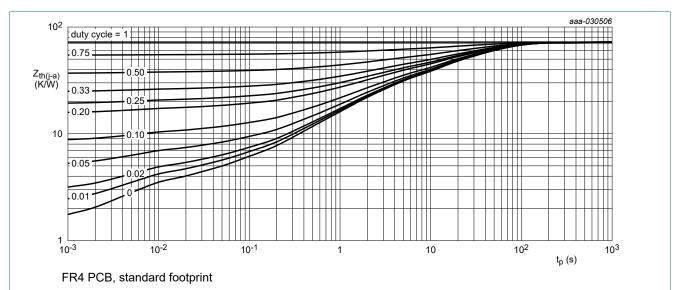
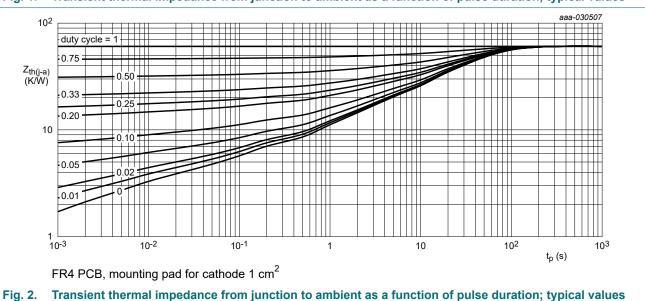


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

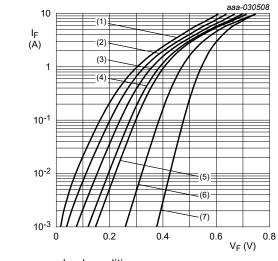


10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per diode (ı	unless otherwise specified	1)					
$V_{(BR)R}$	reverse breakdown voltage	I _R = 1 mA; T _j = 25 °C	[1]	60	-	-	V
V _F	forward voltage	I _F = 0.5 A; T _j = 25 °C	[1]	-	440	510	mV
		I _F = 1 A; T _j = 25 °C	[1]	-	470	540	mV
		I _F = 4 A; T _j = 25 °C	[1]	-	580	660	mV
		I _F = 4 A; T _j = -40 °C	[1]	-	630	720	mV
		I _F = 4 A; T _j = 125 °C	[1]	-	520	610	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	[1]	-	0.14	0.9	μΑ
		V _R = 40 V; T _j = 25 °C	[1]	-	0.18	1.2	μΑ
		V _R = 60 V; T _j = 25 °C	[1]	-	0.3	1.8	μΑ
		V _R = 60 V; T _j = 125 °C	[1]	-	0.5	3	mA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C		-	560	-	pF
		$V_R = 10 \text{ V; } f = 1 \text{ MHz; } T_j = 25 \text{ °C}$		-	180	-	pF
t _{rr}	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 ^{\circ}\text{C}$		-	17	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	11	-	ns
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}; \text{ d}I_F/\text{d}t = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	460	-	mV

^[1] Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1) $T_i = 175 \,^{\circ}C$

(2) $T_i = 150 °C$

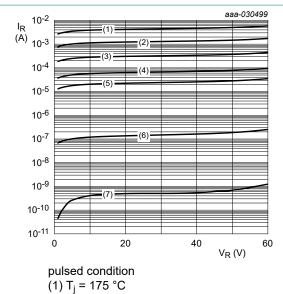
 $(3) T_i = 125 °C$

 $(4) T_i = 100 °C$

(5) $T_j = 85 \,^{\circ}\text{C}$

(6) $T_j = 25 ^{\circ}C$ (7) $T_i = -40 ^{\circ}C$

Fig. 3. Forward current as a function of forward



(2) $T_i = 150 °C$

(3) $T_i = 125 °C$

 $(4) T_j = 100 °C$

(5) $T_j = 85 ^{\circ}C$ (6) $T_i = 25 ^{\circ}C$

 $(7) T_j = -40 ^{\circ}C$

Fig. 4. Reverse current as a function of reverse voltage; typical values

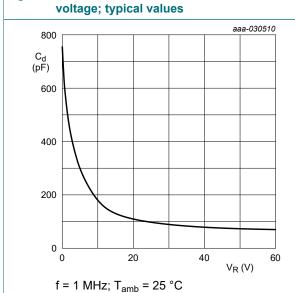
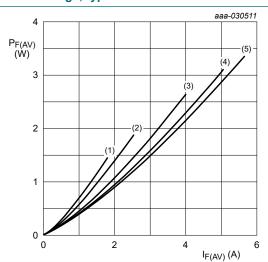


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



 $T_j = 100 \, ^{\circ}C$

 $(1) \delta = 0.1$

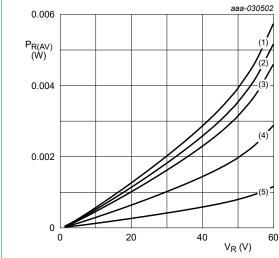
 $(2) \delta = 0.2$

 $(3) \delta = 0.5$

 $(4) \delta = 0.8$

(5) $\delta = 1$; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 100 \, ^{\circ}C$

 $(1) \delta = 1$; DC

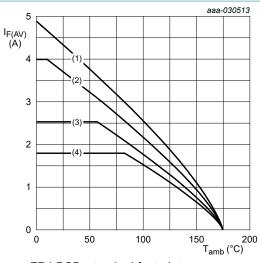
 $(2) \delta = 0.9$

 $(3) \delta = 0.8$

 $(4) \delta = 0.5$

 $(5) \delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 175 °C

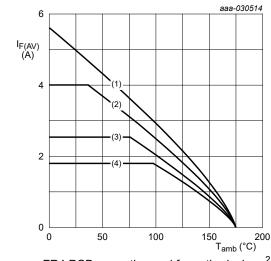
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

T_i = 175 °C

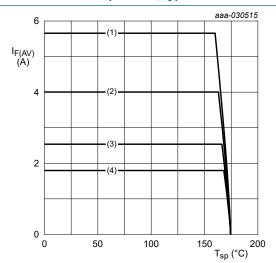
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



 $T_i = 175 \,{}^{\circ}\text{C}$

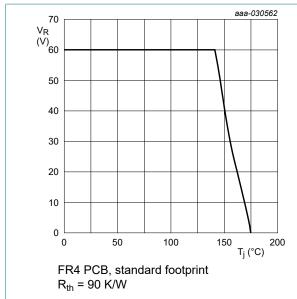
 $(1) \delta = 1$; DC

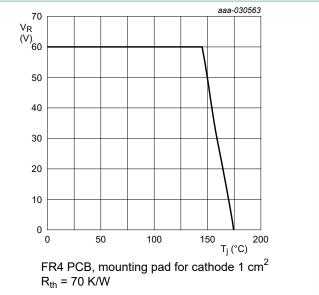
(2) δ = 0.5; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

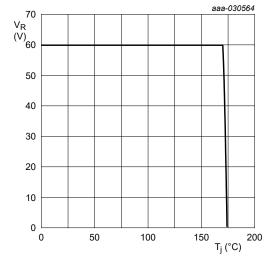
Fig. 10. Average forward current as a function of solder point temperature; typical values





of junction temperature; typical values

Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



Soldering point of cathode tab $R_{th} = 7 \text{ K/W}$

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

11. Test information

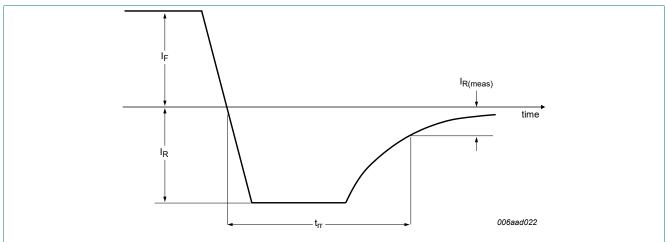


Fig. 14. Reverse recovery definition; step recovery

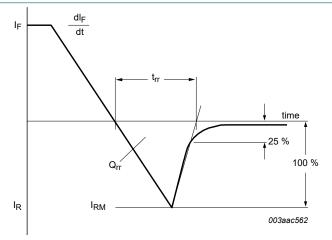


Fig. 15. Reverse recovery definition; ramp recovery

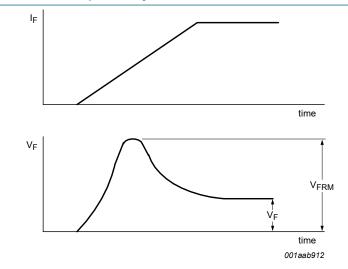
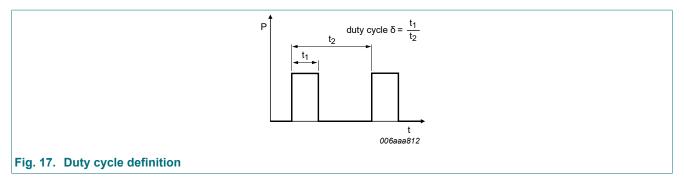


Fig. 16. Forward recovery definition



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

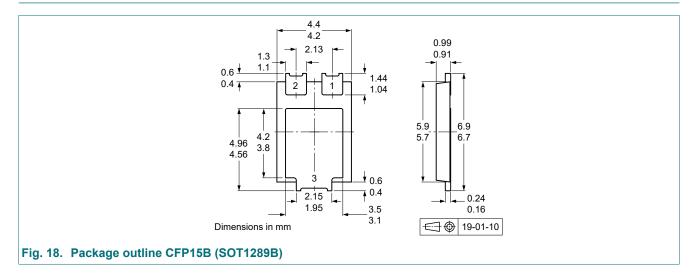
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_{M} \times \sqrt{\delta}$

with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

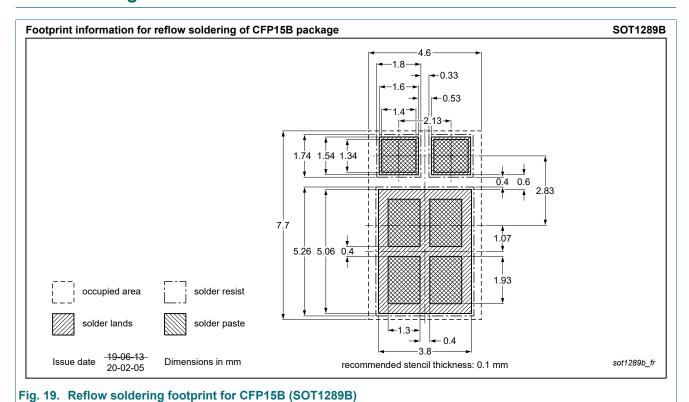
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

dole of Revision matery									
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes					
PMEG060T080CLPE- Q v.2	20210510	Product data sheet	-	PMEG060T080CLPE- Q v.1					
Modifications:	 Features and benefit 	Features and benefits: added recommendation for automotive applications							
PMEG060T080CLPE- Q v.1	20210311	Product data sheet	-	-					

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 10 May 2021

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